

N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- | | |
|-----------------------------------------------------------------|------------------------------------------------------------|
| <input checked="" type="checkbox"/> Advanced trench cell design | <input checked="" type="checkbox"/> Low Thermal Resistance |
| <input checked="" type="checkbox"/> Super Trench | <input checked="" type="checkbox"/> MSL1 |
| <input checked="" type="checkbox"/> T_J max 175°C | |

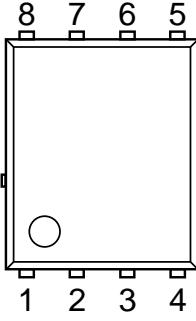
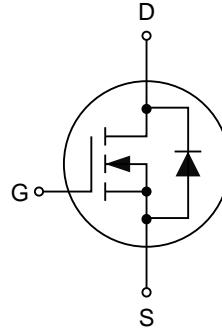
1.2 Applications

- | | |
|---------------------------------------------------|-----------------------------------------------------|
| <input checked="" type="checkbox"/> Motor drivers | <input checked="" type="checkbox"/> DC/DC Converter |
|---------------------------------------------------|-----------------------------------------------------|

1.3 Quick reference

- | | |
|----------------------------------------------------------|--------------------------------------------------------------------------------|
| <input checked="" type="checkbox"/> $BV \geq 40$ V | <input checked="" type="checkbox"/> $R_{DS(ON)} \leq 0.9$ mΩ @ $V_{GS} = 10$ V |
| <input checked="" type="checkbox"/> $P_{tot} \leq 136$ W | |
| <input checked="" type="checkbox"/> $I_D \leq 260$ A | |

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1,2,3	Source		
4	Gate		
5,6,7,8	Drain	 Top View PDFN5x6-8L	

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	Drain-Source Voltage	T _C =25°C	40	-	V
V _{GS}	Gate-Source Voltage	T _C =25°C	-	±20	V
I _D *, ***	Drain Current	T _C =25°C, V _{GS} =10 V	-	260	A
I _D *, ***	Drain Current	T _C =100°C, V _{GS} =10 V	-	183	A
I _{DM} *, **, ***	Pulsed Source Current	T _C =25°C, V _{GS} =10 V	-	780	A
P _{tot} *	Total Power Dissipation	T _C =25°C	-	136	W
T _J , T _{stg}	Operating Junction and Storage Temperature		-55	175	°C
I _S	Diode Forward Current	T _C =25°C	-	260	A
E _{AS}	Single Pulsed Avalanche Energy	V _{DD} =32 V, L=0.5 mH	-	961	mJ
R _{θJA}	Thermal Resistance-Junction to Ambient		-	62.5	°C/W
R _{θJC} *	Thermal Resistance-Junction to Case		-	1.1	

Notes:

* Surface mounted on 1 in² pad area, t ≤ 10 sec.

** Pulse width ≤ 300 μs, duty cycle ≤ 2%.

*** Limited by bonding wire.

4. Marking Information

Product Name	Marking
KJ009N04G	KJ009N04G XXXXXX

5. Ordering Code

Product Name	Package	Reel size	Tape width	Quantity (pcs)
KJ009N04G	PDFN 5x6-8L	13"	12 mm	5000

Note: KUAIJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C).

6. Electrical Characteristics (T_A=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _{DS} =250 μA	40	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250 μA	1.0	1.6	2.2	V
I _{DSS}	Zero Gate Voltage Source Current	V _{DS} =40 V, V _{GS} =0 V	-	-	1	μA
I _{GSS}	Gate Leakage Current	V _{GS} =±20 V, V _{DS} =0 V	-	-	±100	nA
R _{DS(ON)} ^a	Drain-Source On-State Resistance	V _{GS} =10 V, I _{DS} =50 A	-	0.73	0.9	mΩ
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} =20 A, V _{GS} =0 V	-	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =20 A, dI _{SD} /dt=100 A/μs	-	100	-	ns
Q _{rr}	Reverse Recovery Charge		-	64	-	nC
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} =0 V, V _{DS} =20 V, Frequency=1 MHz	-	6250	-	pF
C _{oss}	Output Capacitance		-	2640	-	
C _{rss}	Reverse Transfer Capacitance		-	70	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =20 V, V _{GEN} =10 V, R _G =1.6 Ω, I _{DS} =20 A	-	30	-	ns
t _r	Turn-on Rise Time		-	45	-	
t _{d(off)}	Turn-off Delay Time		-	80	-	
t _f	Turn-off Fall Time		-	34	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{DS} =20 V, V _{GS} =10 V, I _{DS} =20 A	-	126	-	nC
Q _{gs}	Gate-Source Charge		-	30	-	
Q _{gd}	Gate-Drain Charge		-	33	-	

Notes:

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.

7. Typical Characteristics (cont.)

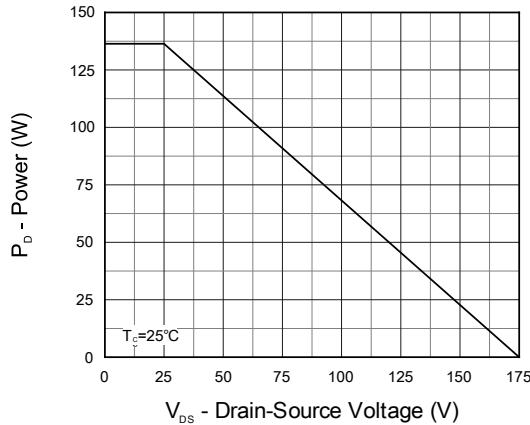


Figure 1. Power Capability

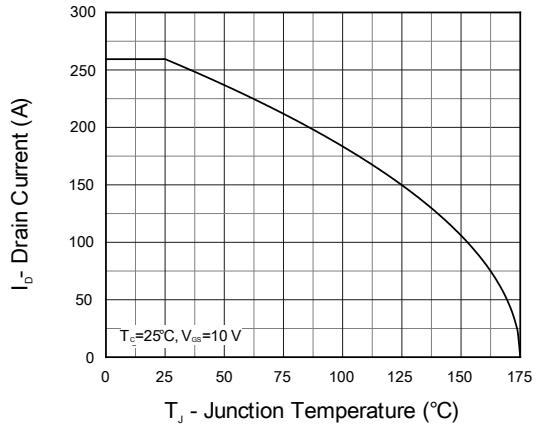


Figure 2. Current Capability

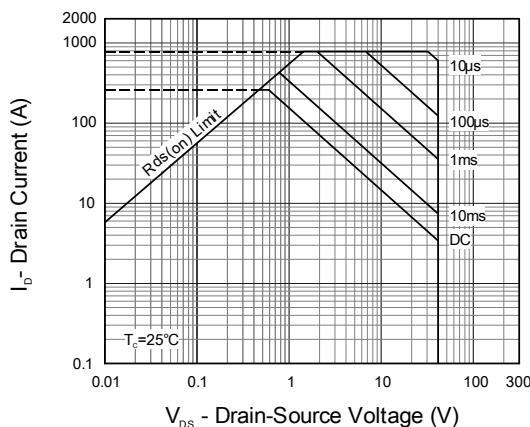


Figure 3. Safe Operation Area

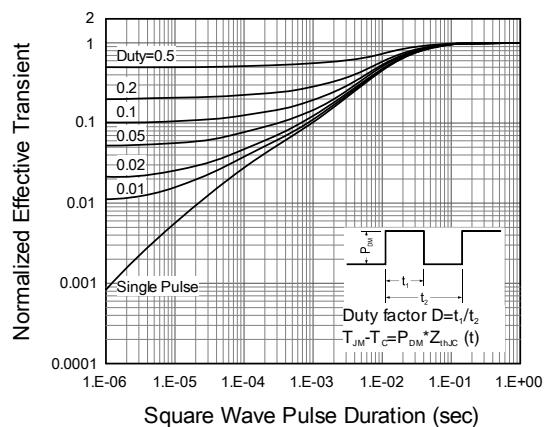


Figure 4. Transient Thermal Impedance

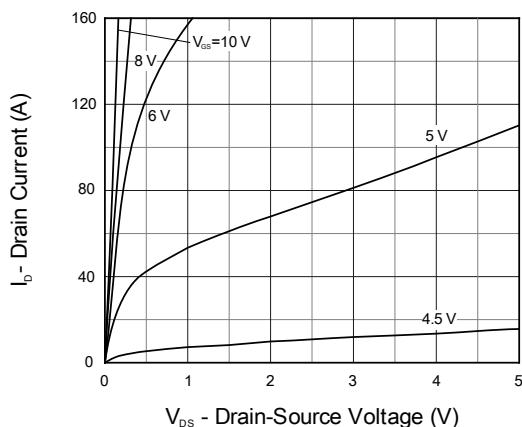


Figure 5. Output Characteristics

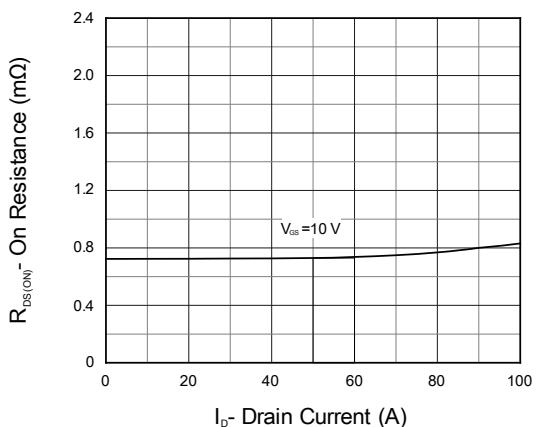


Figure 6. On Resistance

7. Typical Characteristics (cont.)

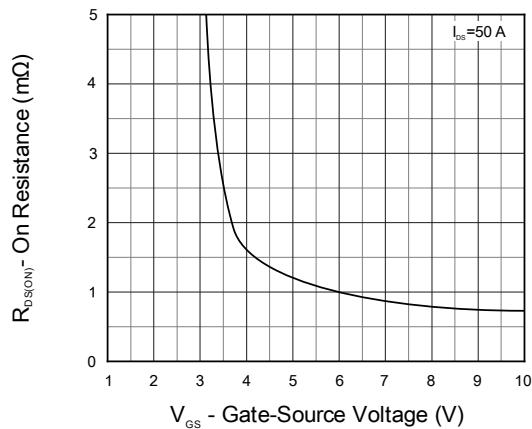


Figure 7. Transfer Characteristics

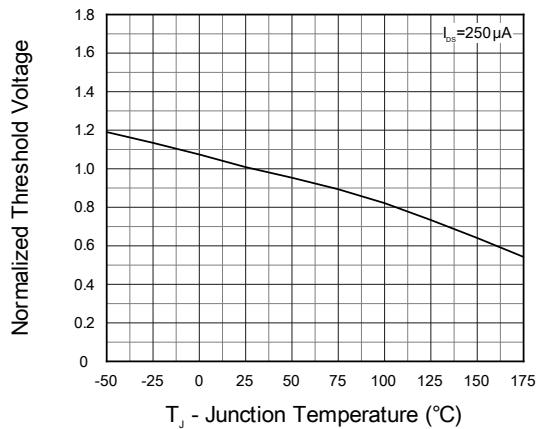


Figure 8. Normalized Threshold Voltage

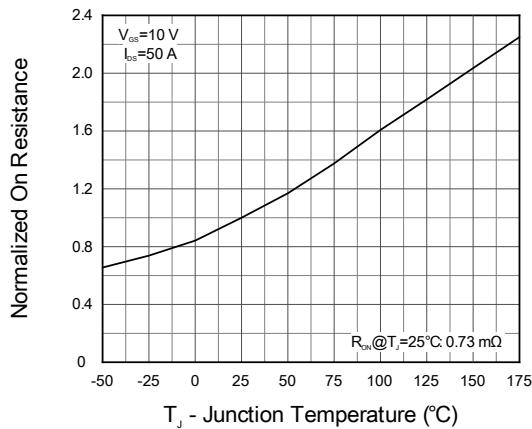


Figure 9. Normalized On Resistance

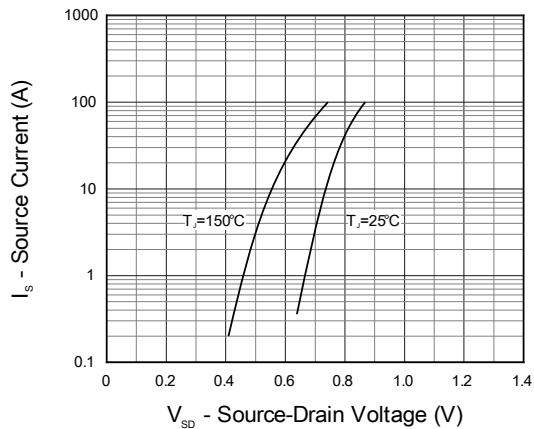


Figure 10. Diode Forward Current

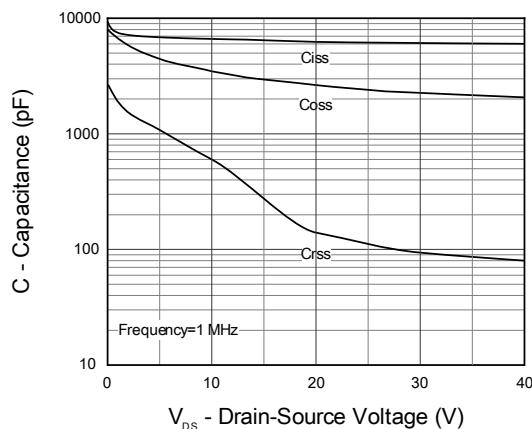


Figure 11. Capacitance

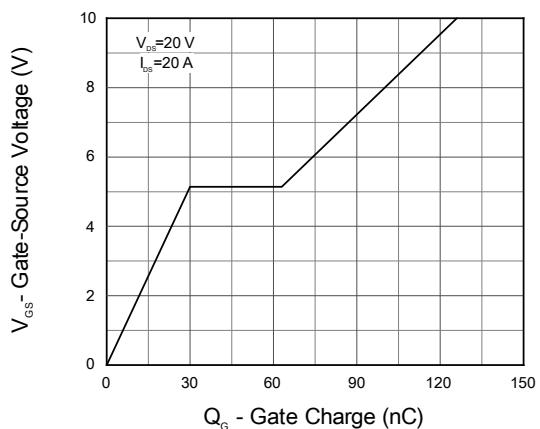
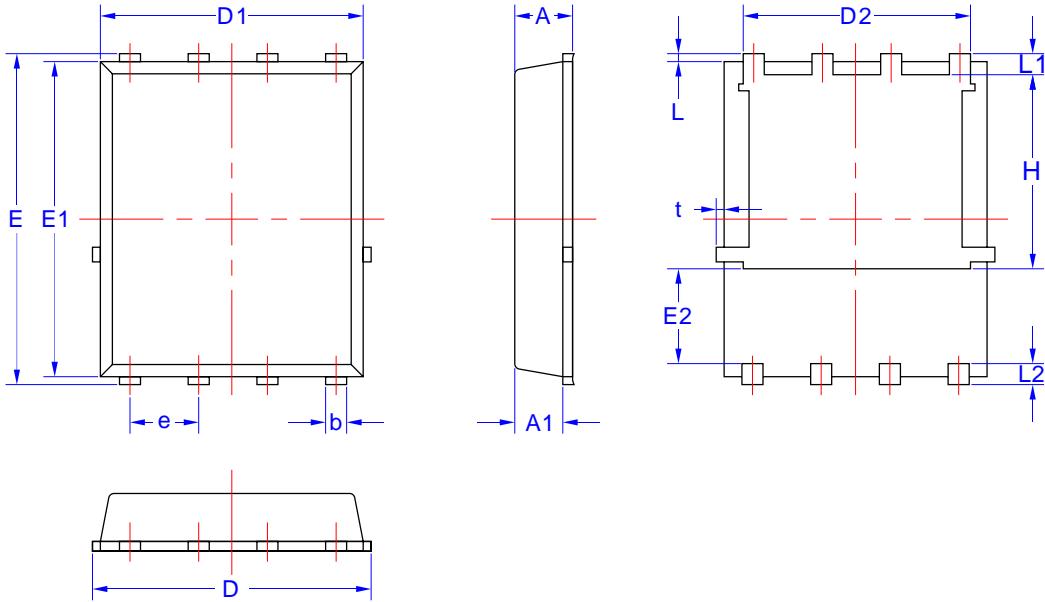


Figure 12. Gate Charge

8. Package Dimensions

PDFN 5x6-8L Package



Symbol	Dimensions in Millimeters	
	MIN.	MAX
A	1.03	1.17
A1	0.824	0.97
b	0.34	0.48
D	4.80	5.40
D1	4.80	5.00
D2	4.11	4.31
E	5.95	6.15
E1	5.65	5.85
E2	1.40	-
e	1.27 BSC	
L	0.05	0.25
L1	0.38	0.50
L2	0.38	0.71
H	3.30	3.50
t	-	0.18